1. An apparatus for encapsulating a circuit on a circuit board, comprising:

a first mold section configured to close on one side of the board, the first mold section having an exposed first conduit;

a second mold section configured to close on another side of the board, the second mold section having a second conduit for pushing molding compound into a mold cavity in at least one of the mold sections, the second conduit having a side opened to the first mold section when the first and section mold sections are closed on the board; and

a piston slidably mounted inside the first conduit and configured to extend toward the second mold section to close the side of the second conduit.

2. The apparatus of claim 1 wherein the board includes a portion that extends over the side of the second conduit, and wherein the piston is configured to crush the portion of the board.

3. The apparatus of claim 2 wherein the piston has a face configured to close the side of the second conduit and a rim extending from the face and configured to crush the portion of the board.

4. The apparatus of claim 3 wherein the rim is arcuate.

5. The apparatus of claim 2 wherein the second mold section has a depression for receiving the board, and wherein the piston has a knife extending from a face and configured to exert force on the board to seat the board against an end stop of the depression when the piston contacts the portion of the board.

6. The apparatus of claim 5 wherein the depression has another knife configured to exert force on the board to seat the board in the depression when the piston contacts the portion of the board.

7. The apparatus of claim 6 wherein the another knife is asymmetric.

8. The apparatus of claim 5 wherein the knife is asymmetric.

9. The apparatus of claim 2 wherein the second mold section has a depression for receiving the board, and wherein the depression has a knife extending from the depression and configured to exert force on the board to seat the board in the depression when the piston contacts the portion of the board.

10. The apparatus of claim 9 wherein the knife is asymmetric.

11. A method for encapsulating a circuit on a circuit board, comprising:

closing a first mold section on one side of the board, the first mold section having an exposed first conduit;

closing a second mold section on another side of the board, the second mold section having a second conduit for pushing molding compound into a mold cavity in at least one of the mold sections, the second conduit having a side opened to the first mold section when the first and section mold sections are closed on the circuit board; and

extending a piston through the first conduit to close the side of the second conduit.

12. The method of claim 11, wherein the board partially extends over the side of the second circuit, further comprising:

crushing a portion of the board extending over the side of the second conduit.

13. The method of claim 11, further comprising:

using the piston to exert lateral forces on the board to seat the board within the second mold section.

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